

Form Type	Distribute	Version	ersion 2.0		Ref		IPC 175	Sectionals		s	Manufacturin Info/ Material Info		Subsectionals	D, A
			•		s	upplier I	nformatio	on						•
Company Name	TE Connectiv		Request Document ID				Name	Revak, David M Conta			act Title	Μg	gr Prod Sustainin	g Engineering
Company Unique ID	TE Connectiv	Response	Response Date		2015-07-15		Contact Email		david.revak@te.com					
Contact Phone	Number	+1-336-664	-1906											
	1					Legal S	tatement							
Supplier Acceptance	true													
Legal Statemen	t													
The information	provided in this	document is base	ed upo	n reasonal	ole inqui	ry of our :	suppliers.	This inf	ormation is	subje	ct to change	. Th	is information doe	es not in any
way modify exist	ing purchase sp	ecifications or ex	isting	contractual	or othe			s betwe	en TE Con	nectivi	ty (or its affili	ated	d companies) and	its customer
Manufacturar	172405 4	A a		0.4		Pro Version	duct			lalam	4:4			
Manufacturer Item number	172495-1	Amount	Amount		8.1		on -			Identity				
Manufacturer Item Name	MIC MK-II PL HSG 7P NATURAL	UG Weight Uo	Weight Uom		g		9			Authority				
Date		иом		Each								1		
EURoHS-0508	Product(s) me	Product(s) meets EU RoHS requirement without any exemptions												
ChinaRoHS- 0508	Product(s) is e	eligible for markir	ng with	the e code	under	China's N	/leasures	for Adm	inistration o	of the	control of pol	lutio	on by Electronic Ir	formation
EUREACH-1214	REACH Cand	idate Substance	s of Ve	ery High Co					Product Ab	ove th	ne Limits per	the	Definition within I	REACH
	1	1			Man		ng Inform	ation				1		
J-STD-020 MSL Rating		Max Total a Wave Time			Ramp R		tate			Wav Addi	e tional Info			
Classification Temp		Max Wave Solder Tim	e	0.0		Ramp Down Rate			Psi F Refle		Rating ow			
Max Time Within 5		Psl Rating	Psl Rating Wave				Package Designator		Size			0.0		
Time Above 217	7	Reflow Additional	Info	0		Preheat Max Temp			Tern		ninal Base	NAC		
Preheat Duration		bulk Solde Terminatio				Nbr or F Cycles				Tern Plati		NAC		
Preheat Min Temp		Nbr of Instances		0		Component Temp Spike			Shap		ре	NA	AC .	
10p		motaneco		l	F		Disclosur	e				1		
Sub- Item/Material/ Substance	Level	Name			stance Substance CAS		Substar Concen		Quantity		Mass per U	nit	UOM	Exemption
Sub-Item	1	MIC MARK-2 PLUG HSG 17P							1.0		8.1		g	
Material	2	PA66							1.0		8.1		g	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier		TE5081-2- 1212		3.0		1.0		0.243		g	
Substance	3	Aluminum, hydroxybis(oct adecanoato- .kappa.O)-	Supplier		300-92-5		0.5		1.0		0.0405		g	
Substance	3	Copper iodide (Cul)	Supplier		7681-65-4		0.05		1.0		0.00405		g	
Substance	3	Aluminum, dihydroxy(octa decanoato- kO)-	Supplier		7047-84-9		0.1		1.0		0.0081		g	
Substance	3	Poly[imino(1,6-dioxo-1,6-hexanediyl)imi no-1,6-hexanediyl]	Supp	Supplier		32131-17-2			1.0		7.72335		g	
Substance	3	Potassium iodide ((KI)	Supp	olier	7681-1	1-0	1.0		1.0		0.081		g	